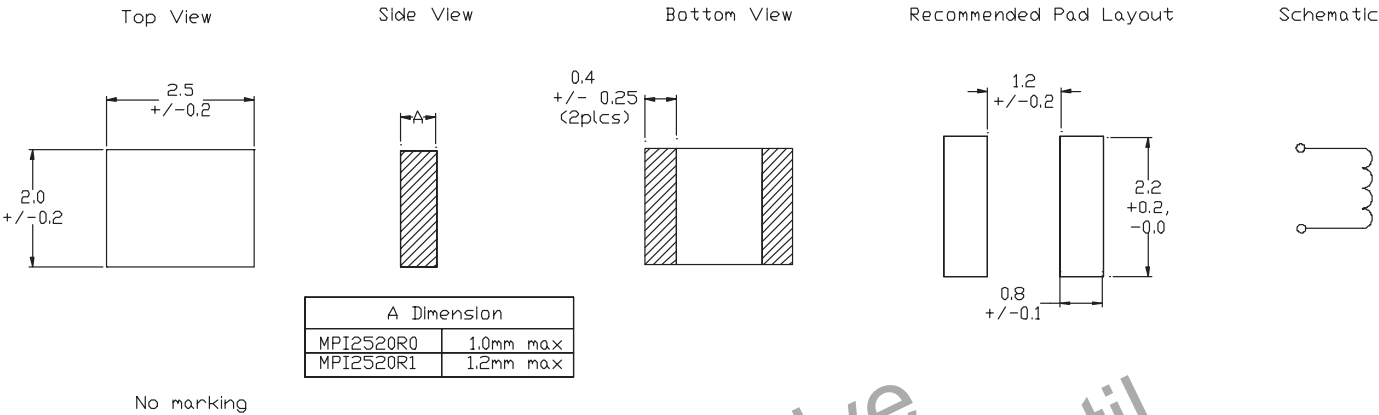


Product specifications

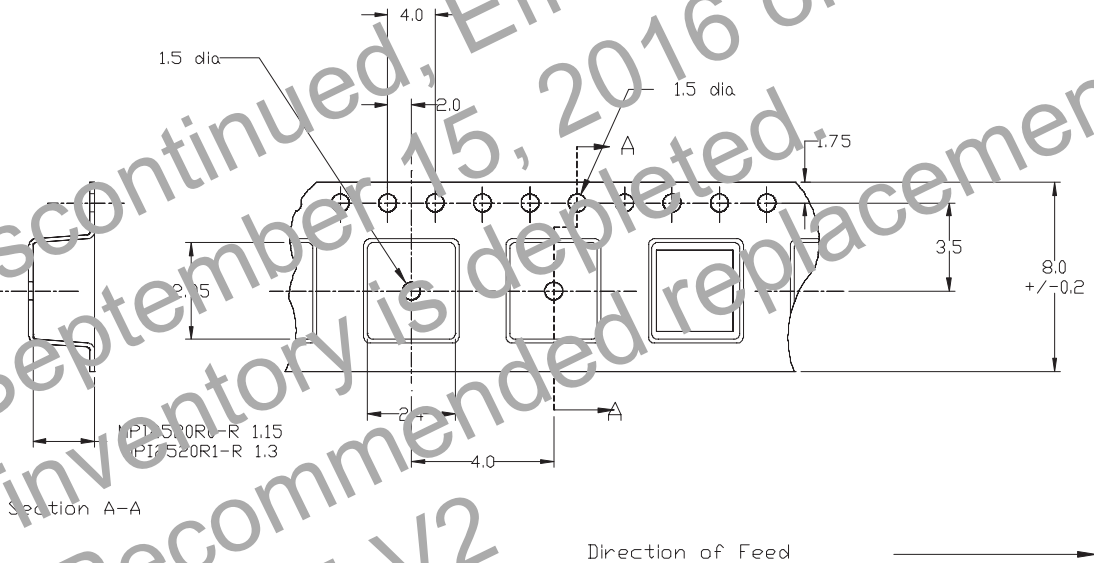
Part Number ⁵	OCL1 (μ H) $\pm 20\%$	I_{rms}^2 (Amps)	I_{sat}^3 (Amps)	DCR (m Ω) @ 25°C typical	DCR (m Ω) @ 25°C max	K-Factor ⁴
R0 — 1.0mm Height						
MPI2520R0-R47-R	0.47	4.1	4.4	28	34	2887
MPI2520R0-1R0-R	0.9	3.2	3.2	50	60	1925
MPI2520R0-1R5-R	1.5	2.4	2.6	80	96	1444
MPI2520R0-2R2-R	2.2	2.2	2.4	103	124	1283
MPI2520R0-3R3-R	3.3	1.6	1.6	190	228	1050
MPI2520R0-4R7-R	4.7	1.4	1.4	240	288	825
R1 - 1.2mm Height						
MPI2520R1-R47-R	0.47	4.5	4.8	20	24	2310
MPI2520R1-1R0-R	1.0	3.7	4.0	35	42	1925
MPI2520R1-1R5-R	1.5	2.9	3.2	55	66	1444
MPI2520R1-2R2-R	2.2	2.3	2.7	75	90	1255
MPI2520R1-3R3-R	3.3	1.8	2.4	105	126	962
MPI2520R1-4R7-R	4.7	1.6	1.9	150	180	825
MPI2520R1-5R6-R	5.6	1.5	1.5	200	240	679
MPI2520R1-6R8-R	6.8	1.3	1.3	300	360	679
MPI2520R1-100-R	10.0	1.1	1.2	390	468	525

1. Open Circuit Inductance (OCL) Test Parameters: 1MHz, 0.1Vrms, 0.0A dc, 25°C
2. I_{rms} : DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +25°C under worst case operating conditions verified in the end application.
3. I_{sat} : Peak current for approximately 10% rolloff at +25°C
4. K-factor: Used to determine B_{pp} for core loss (see graph).
 $B_{pp} = K \sqrt{L \Delta I}$; B_{pp} (Gauss), K : (K-factor from table),
 L : (Inductance in μ H), ΔI (Peak to peak ripple current in Amps).
5. Part Number Definition: MPI2520Rx-yyy-R
 - MPI2520Rx = Product code and size
 - yyy = Inductance value in μ H, R = decimal point,
 if no R is present then third character = number of zeros.
 - "-R" suffix = RoHS compliant

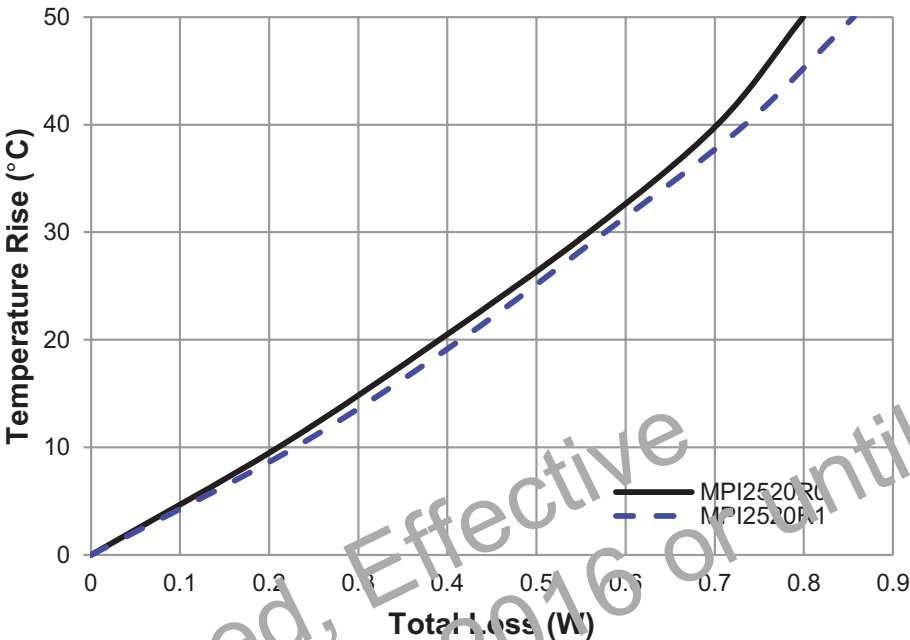
Dimensions - mm



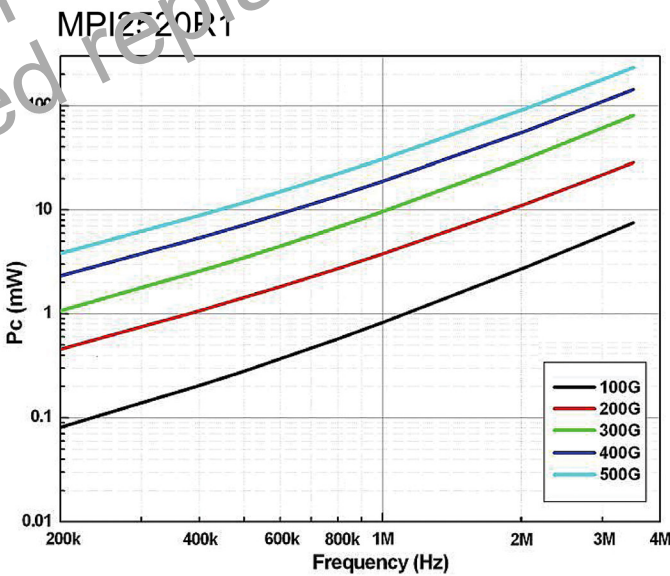
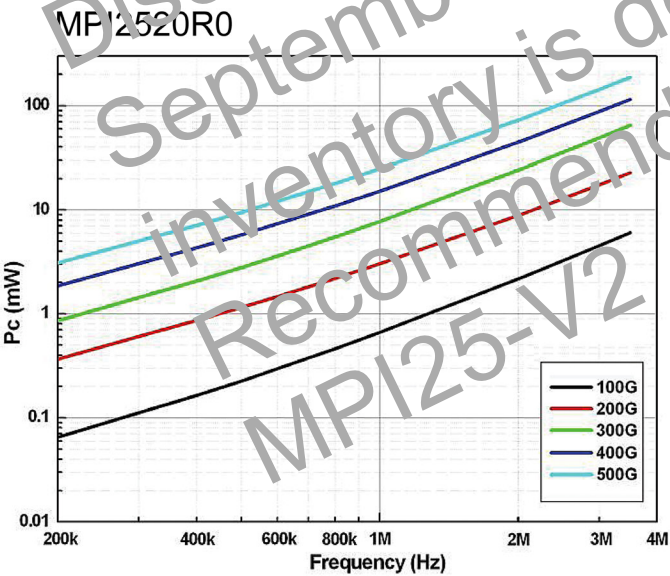
Packaging information - mm



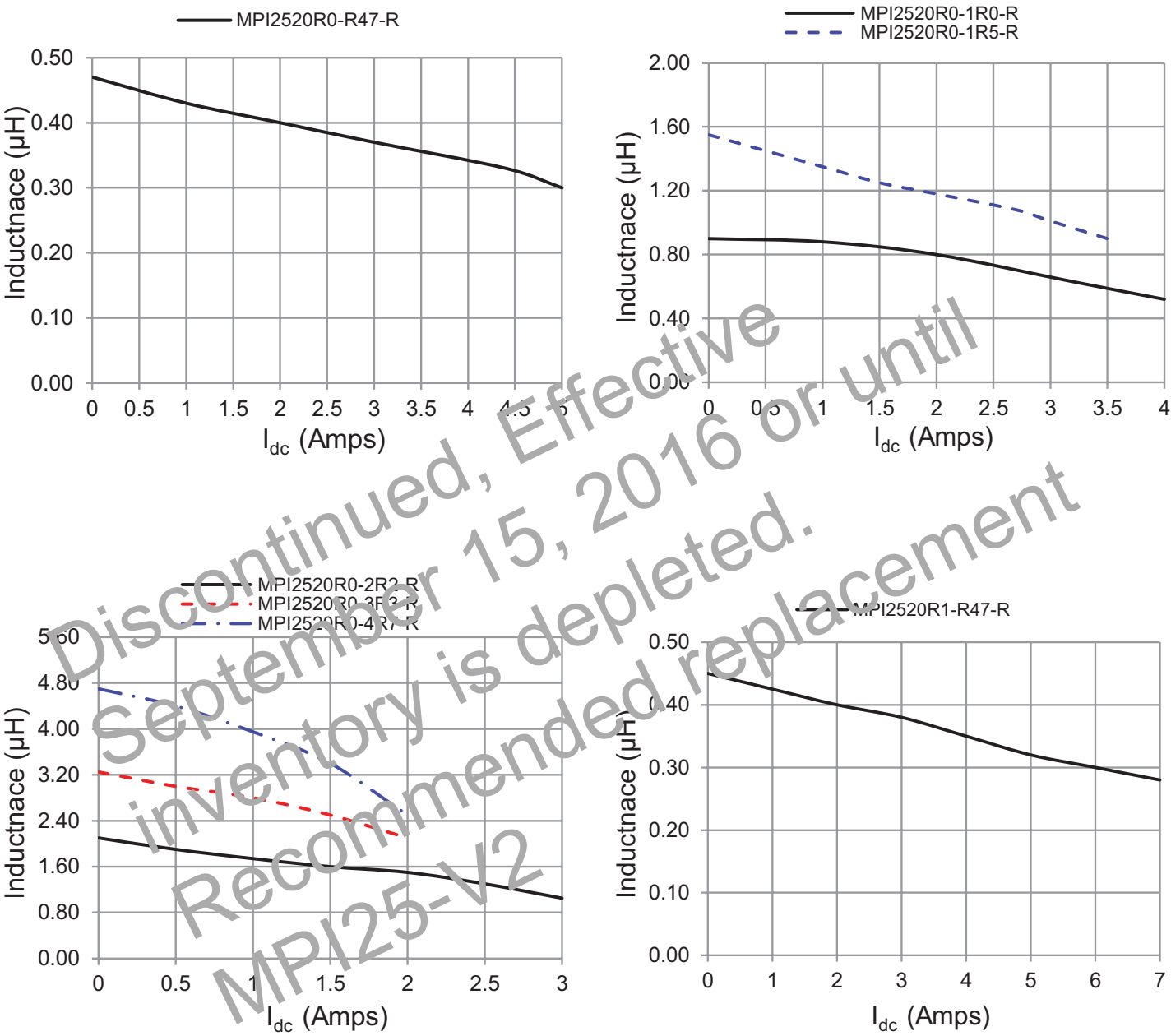
Temperature rise vs. total loss



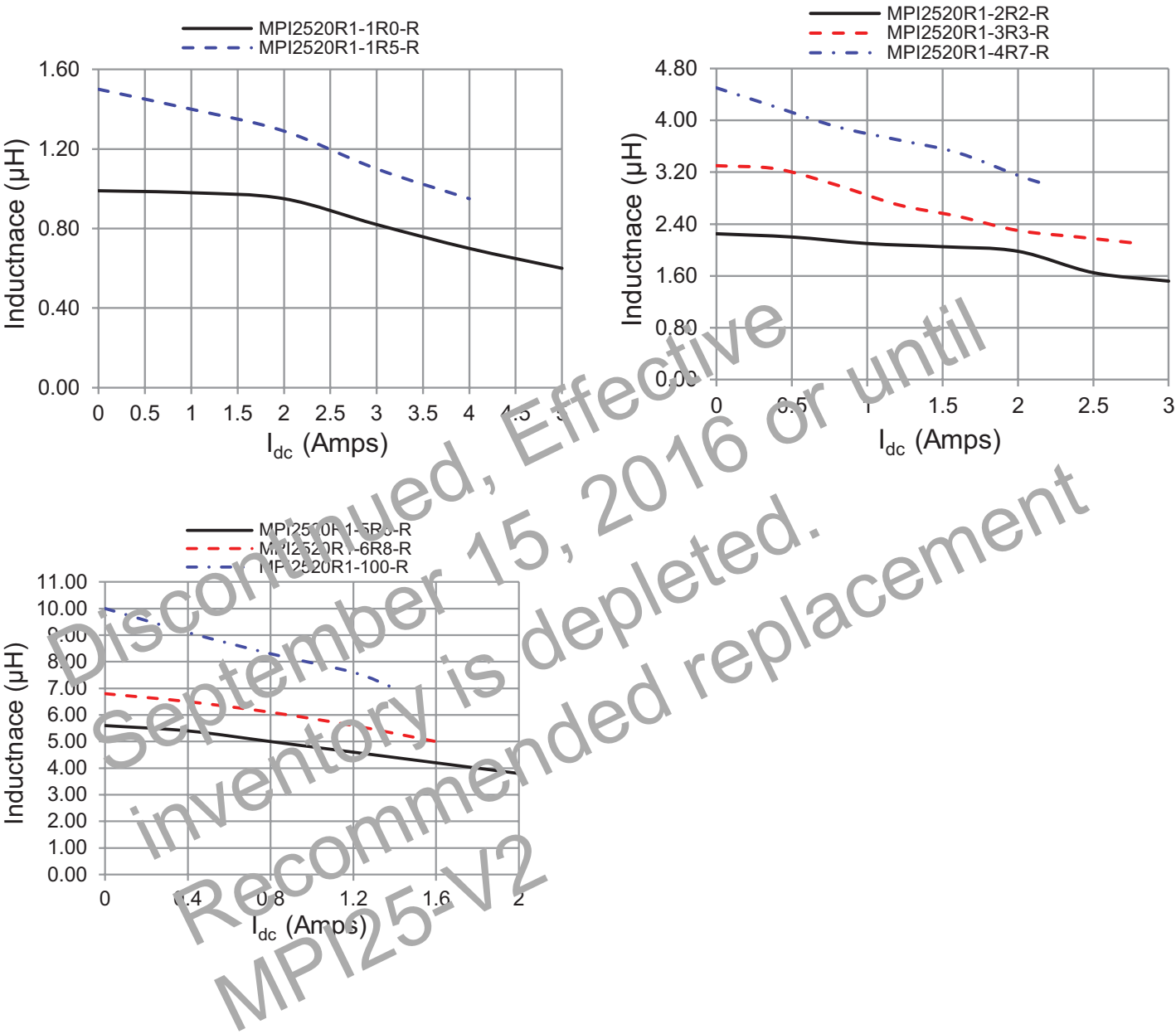
Core loss



Inductance characteristics



Inductance characteristics



Solder reflow profile

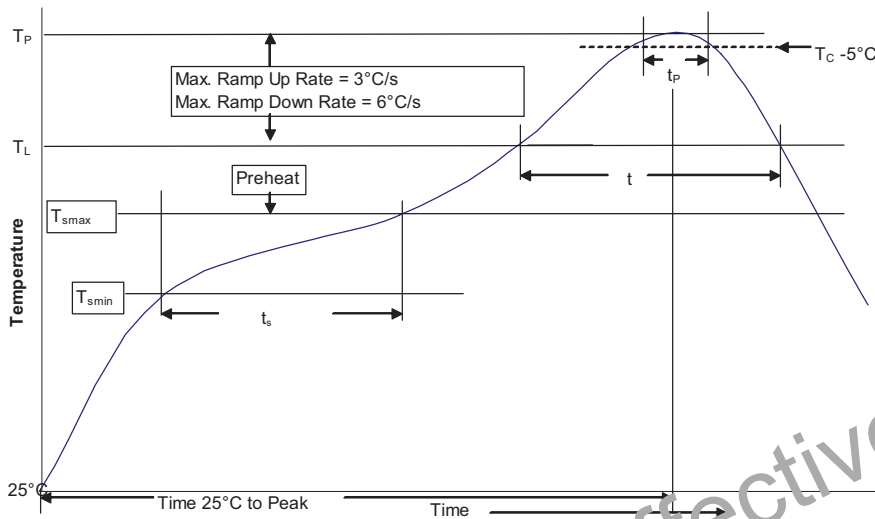


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume ≤ 350 mm ³	Volume ≥ 350 mm ³
<2.5mm	235°C	220°C
≥ 2.5 mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume ≤ 350 mm ³	Volume 350 - 2000 mm ³	Volume > 2000 mm ³
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
> 2.5 mm	250°C	245°C	245°C

Reference JEDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	50°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidus temperature (T_L)	183°C	217°C
Time at Liquidus (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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